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## OCP-IP Hosts Conference Within a Conference at DATE

**PORTLAND, Ore. — March 1, 2005** — The Open Core Protocol International Partnership (OCP-IP) will feature a conference-within-conference program at the Design Automation and Test Exhibition (DATE) held 7-11 March 2005, in Munich Germany. The Pavilion will host exhibits from several OCP-IP member companies including Sonics, CAST and MIPS, and an open discussion forum in the midst of Europe's largest electronic system design exhibition. The pavilion program will combine expert panel sessions and papers, offering visitors a view into key technical trends and insight into the future SoC market.

Papers and panels will encompass the diverse issues surrounding re-usable IP, such as: IP development, purchasing, interconnect, verification and testing, IP quality, Network on Chip (NoC) and more.

Presentations will be given by many OCP-IP member companies including: Accent, CoWare, First Silicon Solutions, MIPS, Nokia, Prosilog, Texas Instruments, TransEDA, Yogitech, and more. Panels will include: "Network on a Chip: Great idea, but where are the implementations?" "IP from Silicon Vendors: Good or bad?" "New Paradigm for Design Excellence: What's on the Horizon?" moderated by Gary Smith, and "What is EDA Missing?" hosted by Ulf Schlichtmann, University of Munich.

For more information on the OCP-IP DATE Pavilion see [www.ocpip.org](http://www.ocpip.org).

### **About OCP-IP**

The OCP International Partnership Association, Inc. (OCP-IP) formed in 2001, promotes and supports the Open Core Protocol (OCP) as the complete socket standard ensuring rapid creation and integration of interoperable virtual components. OCP-IP's Governing Steering Committee participants are: Nokia [NYSE: NOK], Texas Instruments [NYSE: TXN], STMicroelectronics [NYSE: STM], Toshiba Semiconductor Group (including Toshiba America TAEC), and Sonics. OCP-IP is a non-profit corporation delivering the first fully supported, openly licensed, core-centric protocol comprehensively fulfilling system-level integration requirements. The OCP facilitates IP core reusability and reduces design time, risk, and manufacturing costs for SoC designs. VSIA endorses the OCP socket, and OCP-IP is affiliated with the VSI Alliance. For additional background and membership information, visit [www.OCP-IP.org](http://www.OCP-IP.org).

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